

2-1. CDMA General Specification

ITEM	CDMA
Tx Freq. range	824.04~848.97MHz
Rx Freq. range	869.04~893.97MHz
Channel Bandwidth	1.23MHz
Channel Spacing	30KHz
Number of Channel	832
Duplex Separation	45MHz
In/Output Impedance	50Ohm
Tx Local Frequency	F _{Tx} * 1.6666
Rx Local Frequency	F _{Rx} * 2
TCXO Frequency	19.2MHz
Freq. Stability	(FRX-45MHz)±300Hz
Operating Temperature	-30℃ ~+60℃





lte	em	GSM 850	EGSM 900	DCS1800	PCS1900
Freq. Ba Uplink/D		824~849 869~894	880~915 925~960	1710~1785 1805~1880	1850~1910 1930~1990
ARFCN	l range	128~251	0~124 & 975~1023	512~885	512~810
Tx/Rx s	spacing	45MHz	45MHz	95MHz	80MHz
Mod. B		270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us
Time Slo Frame		576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms
Modulation	GSM/ GPRS	0.3GMSK	0.3GMSK	0.3GMSK	0.3GMSK
MS P	'ower	33dBm ~5dBm	33dBm ~5dBm	30dBm ~0dBm	30dBm ~0dBm
Power	Class	5pcl ~ 19pcl	5pcl ~ 19pcl	0pcl ~ 15pcl	0pcl ~ 15pcl
Sens	itivity	-102dBm	-102dBm	-100dBm	-100dBm
TDMA	A Mux	8	8	8	8
Cell R	adius	35Km	35Km	2Km	2Km



2-2. GSM Tx Power Class

TX Power control level	GSM850	TX Power control level	EGSM900	TX Power control level	DCS1800	TX Power control level	PCS1900
5	33±2 dBm	5	33±2 dBm	0	30±3 dBm	0	30±3 dBm
6	31±2 dBm	6	31±2 dBm	1	28±3 dBm	1	28±3 dBm
7	29±2 dBm	7	29±2 dBm	2	26±3 dBm	2	26±3 dBm
8	27±2 dBm	8	27±2 dBm	3	24±3 dBm	3	24±3 dBm
9	25±2 dBm	9	25±2 dBm	4	22±3 dBm	4	22±3 dBm
10	23±2 dBm	10	23±2 dBm	5	20±3 dBm	5	20±3 dBm
11	21±2 dBm	11	21±2 dBm	6	18±3 dBm	6	18±3 dBm
12	19±2 dBm	12	19±2 dBm	7	16±3 dBm	7	16±3 dBm
13	17±2 dBm	13	17±2 dBm	8	14±3 dBm	8	14±3 dBm
14	15±2 dBm	14	15±2 dBm	9	12±4 dBm	9	12±4 dBm
15	13±2 dBm	15	13±2 dBm	10	10±4 dBm	10	10±4 dBm
16	11±3 dBm	16	11±3 dBm	11	8±4 dBm	11	8±4 dBm
17	9±3 dBm	17	9±3 dBm	12	6±4 dBm	12	6±4 dBm
18	7±3 dBm	18	7±3 dBm	13	4±4 dBm	13	4±4 dBm
19	5±3 dBm	19	5±3 dBm	14	2±5 dBm	14	2±5 dBm
-	-	-	-	15	0±5 dBm	15	0±5 dBm



2-3. WCDMA General Specification

	WCDMA2100	WCDMA1900	WCDMA850	WCDMA900
Freq. Band[MHz]	1922~1977	1852~1907	824~849	880~915
Uplink/Downlink	2112~2167	1932~1987	869~894	925~960
ARFCN range	UL: 9612~9888	UL: 9262~9538	UL: 4132~4233	UL: 2712~2863
ARPONTAILIGE	DL: 10562~10838	DL: 9662~9938	DL: 4357~4458	DL: 2937~3088
Tx/Rx spacing	190MHz	80MHz	45MHz	45MHz
Mod. Bit rate/ Bit Period	3.84 Mcps	3.84 Mcps	3.84 Mcps	3.84 Mcps
Time Slot Period/Frame	FrameLength:10ms	FrameLength:10ms	FrameLength:10ms	FrameLength:10ms
Period	Slotlength:0.667ms	Slotlength:0.667ms	Slotlength:0.667ms	Slotlength:0.667ms
Modulation	QPSK/HQPSK	QPSK/HQPSK	QPSK/HQPSK	QPSK/HQPSK
MS Power	24dBm~-50dBm	24dBm~-50dBm	24dBm~-50dBm	24dBm~-50dBm
Power Class	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)
Sensitivity	-106.7dBm	-106.7dBm	-106.7dBm	-106.7dBm
TDMA Mux	8	8	8	8
Cell Radius	2Km	2Km	2Km	2Km



2-4. TD-SCDMA General Specification

	Band34	Band39
Freq. Band[MHz] Uplink/Downlink	2010~2025	1880~1920
ARFCN range	10054~10121	9404~9596
Tx/Rx spacing	/	/
TCXO Frequency	19.2MHz	19.2MHz
Modulation	QPSK/16-QAM	QPSK/16-QAM
MS Power	-49dBm~ 25dBm	-49dBm~ 25dBm
Power Class	2 (max: 24 +1/-3dBm)	2 (max: 24 +1/-3dBm)
Sensitivity	-108dBm/1.28MHz	-108dBm/1.28MHz
Cell Radius	>10Km	>10Km
In/Output Impedance	50Ω	50Ω
Operating Temperature	-30℃ ~ +60℃	-30℃ ~ +60℃



2-5. LTE General Specification(FDD)

	Band1 (FDD)	Band3 (FDD)	Band5 (FDD)	Band7 (FDD)	Band8 (FDD)
Freq. Band[MHz]	1920~1980	1710~1785	824~849	2500~2570	880~915
UL/DL	2110~2170	1805~1880	869~894	2620~2690	925~960
ARFCN range	18000~18599	19200~19949	20400~20649	20750~20449	21450~21799
UL/DL	0~599	1200~1949	2400~2649	2750~3449	3450~3799
Tx/Rx spacing	190MHz	95MHz	45MHz	120MHz	45MHz
TCXO Frequency	19.2MHz	19.2MHz	19.2MHz	19.2MHz	19.2MHz
Modulation	QPSK/16-QAM/64-	QPSK/16-QAM/64-	QPSK/16-QAM/64-	QPSK/16-QAM/64-	QPSK/16-QAM/64-
Modulation	QAM	QAM	QAM	QAM	QAM
MS Power	-40dBm~ 25dBm				
Power Class	3 (max: 23 ±2dBm)				
Sensitivity (10M)	-100	-100	-100	-98	-100
Cell Radius	>5Km	>5Km	>5Km	>5Km	>5Km
In/Output Impedance	50Ω	50Ω	50Ω	50Ω	50Ω
Operating Temperature	-30°C ~ +60°C				



2-6. LTE General Specification(TDD)

	Band34 (TDD)	Band38 (TDD)	Band39 (TDD)	Band40 (TDD)	Band41 (TDD)
Freq. Band[MHz] Uplink/Downlink	2010~2025	2570~2620	1880~1920	2300~2400	2555~2655
ARFCN range	36225~36325	37750~38249	38250~38649	38650~39649	40240~41240
Tx/Rx spacing	/	/	/	/	/
TCXO Frequency	19.2MHz	19.2MHz	19.2MHz	19.2MHz	19.2MHz
Modulation	QPSK/16-QAM/64- QAM	QPSK/16-QAM/64- QAM	QPSK/16-QAM/64- QAM	QPSK/16-QAM/64- QAM	QPSK/16-QAM/64- QAM
MS Power	-40dBm~ 25dBm				
Power Class	3 (max: 23 ±2dBm)				
Sensitivity (10M)	-100	-100	-100	-100	-100
Cell Radius	>5Km	>5Km	>5Km	>5Km	>5Km
In/Output Impedance	50Ω	50Ω	50Ω	50Ω	50Ω
Operating Temperature	-30℃ ~ +60℃	-30℃ ~ +60℃	-30℃ ~ +60℃	-30℃ ~ +60℃	-30℃ ~ +60℃





Main Function

Item	Description			
os	Android V7.0 (Nougat OS)			
RF	2G Quad(850/900/1800/1900), CDMA(800),WCDMA(1,2,5,8), LTE (1,3,5,7,8,34,38,39,40,41), TD-SCDMA(34,39)			
Battery	2,600mAh			
Base Band	1.4GHz Quad			
Other RF	GPS, Glonass, Beidou, BT4.2, USB 2.0, WIFI 802.11 b/g/n SISO, NFC			
Camera	13MP AF (Main). 5M FF(Front)			
LCD	5" HD in Cell Touch LCD, 1280 x 720			
RAM	4GB LPDDR3 RAM + 32GB eMMC			
Sensor	Accelerometer, Proxy			
Accessory	Charger: 5V, 1.5A Headset (Option)			

9. Reference Abbreviate



Reference Abbreviate

- AAC: Advanced Audio Coding.— AVC: Advanced Video Coding.
- BER: Bit Error Rate
- BPSK: Binary Phase Shift Keying
- CA : Conditional Access
- CDM : Code Division Multiplexing
- C/I: Carrier to Interference
- DMB: Digital Multimedia Broadcasting
- EN: European StandardES: Elementary Stream
- ETSI: European Telecommunications Standards Institute
- MPEG: Moving Picture Experts Group
- PN: Pseudo-random Noise
- PS: Pilot Symbol
- QPSK: Quadrature Phase Shift Keying
- RS : Reed-SolomonSI : Service Information
- TDM: Time Division Multiplexing
- TS: Transport Stream

1. Safety Precautions



1-1. Repair Precaution

Before attempting any repair or detailed tuning, shield the device from RF noise or static electricity discharges.

Use only demagnetized tools that are specifically designed for small electronic repairs, as most electronic parts are sensitive to electromagnetic forces.

Use only high quality screwdrivers when servicing products. Low quality screwdrivers can easily damage the heads of screws.

Use only conductor wire of the properly gauge and insulation for low resistance, because of the low margin of error of most testing equipment.

We recommend 22-gauge twisted copper wire.

Hand-soldering is not recommended, because printed circuit boards (PCBs) can be easily damaged, even with relatively low heat. Never use a soldering iron with a power rating of more than 100 watts and use only lead-free solder with a melting point below 250°C (482°F).

Prior to disassembling the battery charger for repair, ensure that the AC power is disconnected. Always use the replacement parts that are registered in the SEC system. Third-party replacement parts may not function properly.

1. Safety Precautions



1-2. ESD(Electrostatically Sensitive Devices) Precaution

Many semiconductors and ESDs in electronic devices are particularly sensitive to static discharge and can be easily damaged by it. We recommend protecting these components with conductive anti-static bags when you store or transport them.

Always use an anti-static strap or wristband and remove electrostatic buildup or dissipate static electricity from your body before repairing ESDs.

Ensure that soldering irons have AC adapter with ground wires and that the ground wires are properly connected.

Use only desoldering tools with plastic tips to prevent static discharge.

Properly shield the work environment from accidental electrostatic discharge before opening packages containing ESDs.

The potential for static electricity discharge may be increased in low humidity environments, such as air-conditioned rooms. Increase the airflow to the working area to decrease the chance of accidental static electricity discharges.



6-1. S/W Download

6-1-1. Prepare for S/W Downloading

- Installation program: Downloader Program (Odin3 v3.11.exe)
- Mobile Phone
- Data Cable
- Mobile device specific S/W: Binary files

X Settings



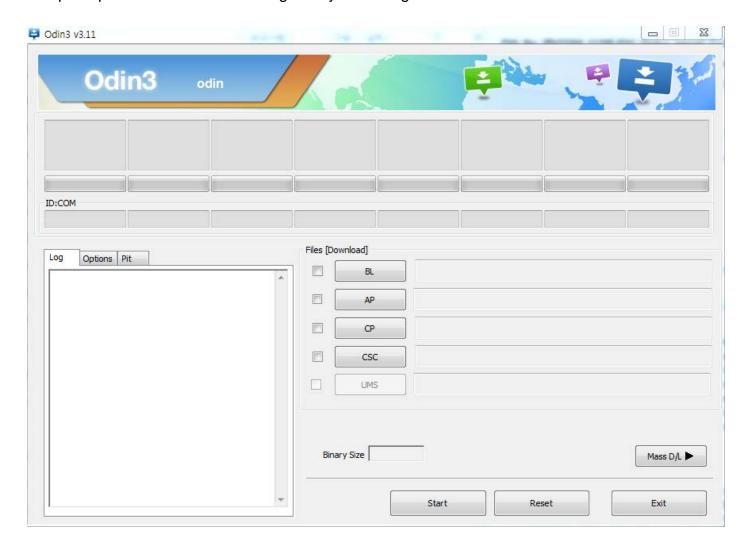


Data Cable: GH39-01710D



6-1-2. S/W Installation Program (Downloader program)

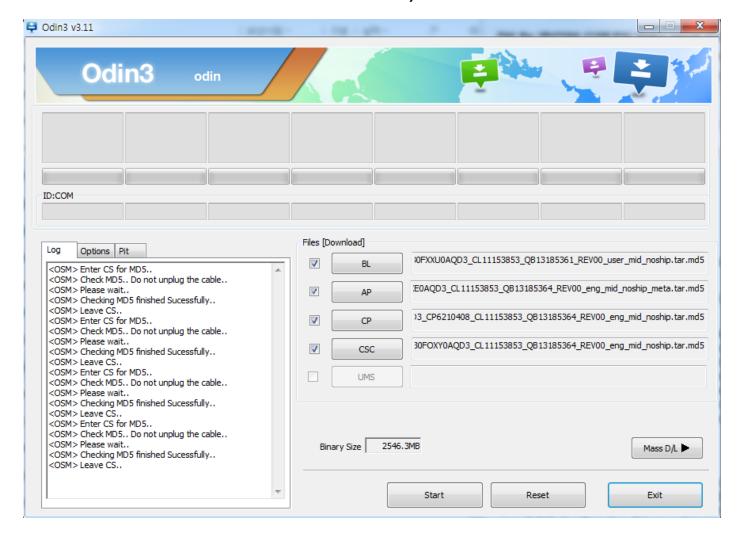
■ Open up the S/W Installation Program by executing the "Odin3 v3.11.exe"





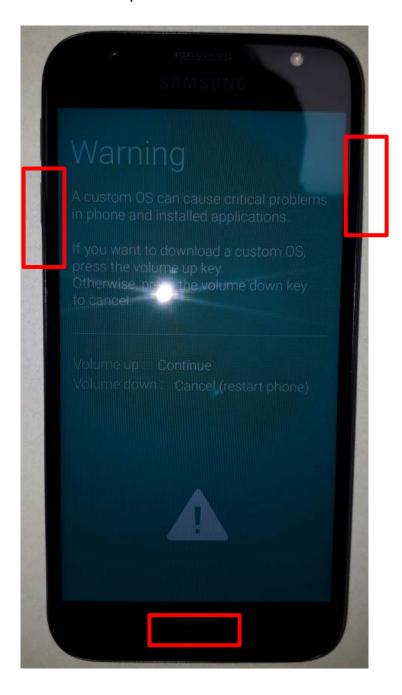


- 1. Enable the check mark by click on the following options,
- Check Auto Reboot, Re-Partition, and F. Reset Time
- Check PIT
- Check BOOTLOADER, PDA, PHONE, and CSC Files
- * Note: "Odin v3.09 or above" checks MD5 checksum just after file selection.





- 2. Enter into Download Mode
- Enter into Download Mode by pressing Volume Down, Home and Power button simultaneously followed by pressing
- Volume up button as a direction of the phone.

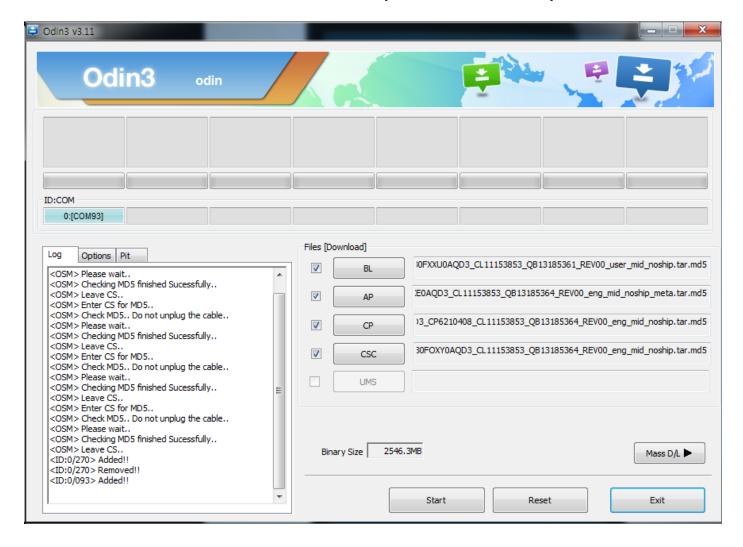






3. Connect the device to PC via Data Cable.

Make sure that the one of communication ports [ID:COM] box is highlighted in sky blue. The device is now connected with the PC and ready to download the binary files in it.



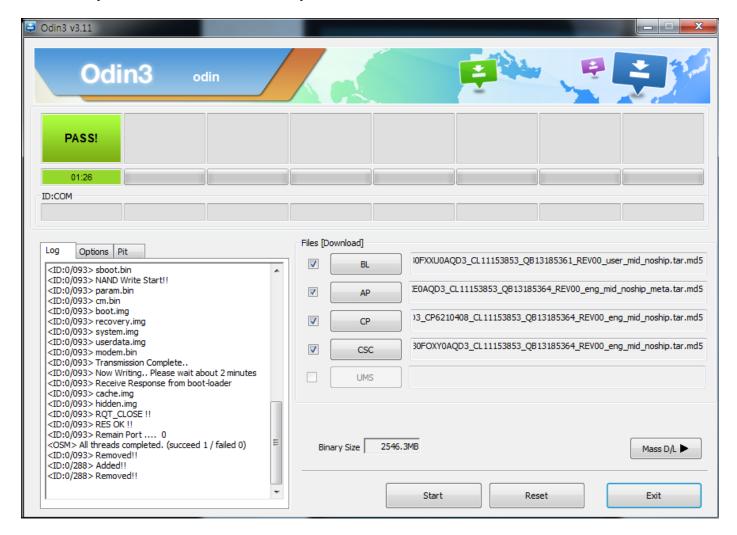




4. Start downloading the binary files into the device by clicking Start button on the screen.

The green colored "PASS!" sign will appear on the upper-left box.

If the binary files have been successfully downloaded into the device.



- Disconnect the device from the Data cable.
- **6**. Once the device boots up, you can check the version of the binary file or name by pressing the following code in sequence; *#1234#

You can perform Factory Reset by Settings → Accounts → Backup and reset

X Caution, Never disconnect during the S/W downloading.

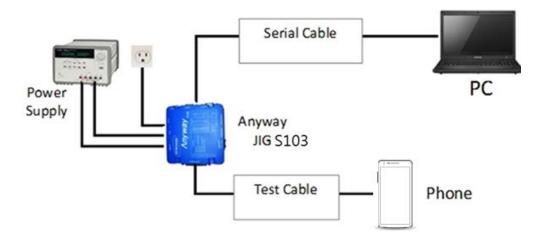


6-2 IMEI writing

6-2-1 Preparation

- New IMEI writing Program has been released.
- Supported Model: Models which CAB files are uploaded on HHPsvc INI File category, instead of ini file.
- Refer to below IMEI writing procedure.

- H/W

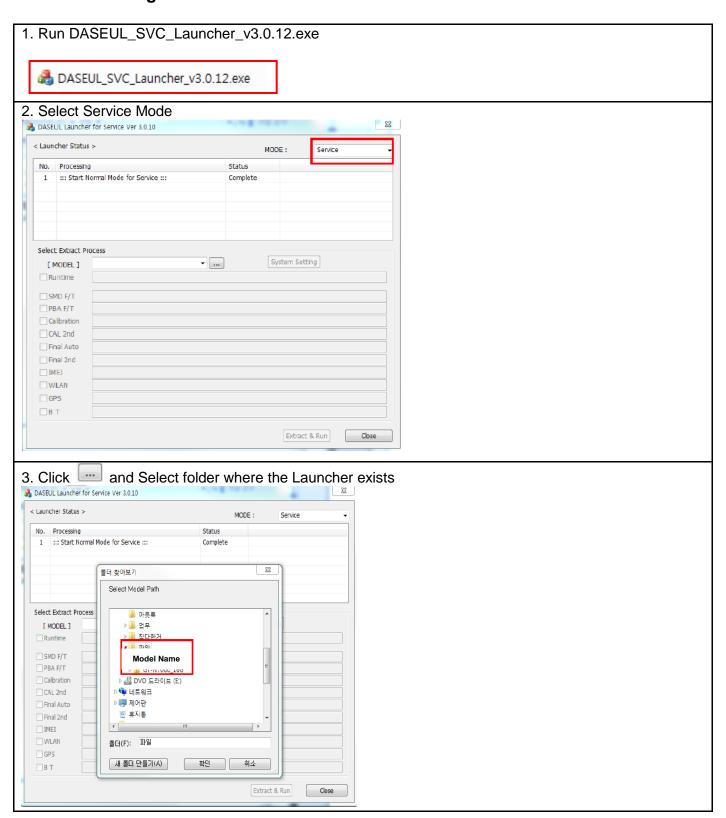


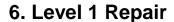
- S/W

① Library Install	To use Daseul, library files should be installed. Refer to SVC Bulletin "(11-82) Daseul (New IMEI writing Program) Library Install guide_rev1.0"
2Launcher	DASEUL_SVC_Launcher_v3_0_25 or higher -Uploaded on HHPsvc Notice
③ Runtime File	DASEUL_Runtime_Ver_3.1.139.0.CAB or higher -Uploaded on HHPsvc Notice Make 'ModelName' folder at the same position with launcher & Runtime file.
4Model File	Copy Model File under the 'Model Name' folder

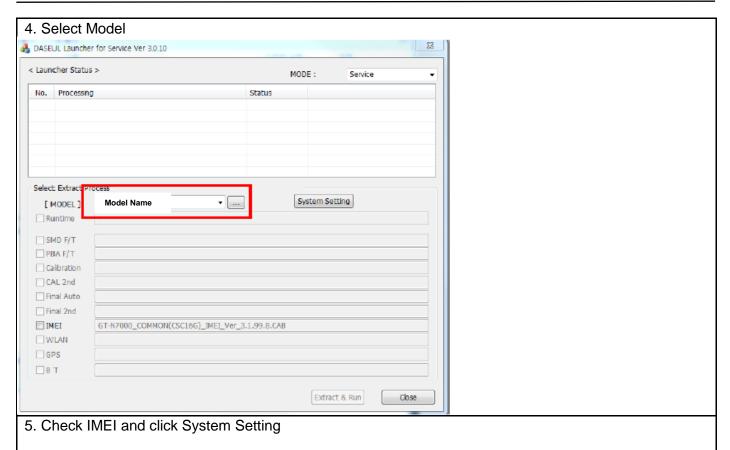


6-2-2 IMEI writing Process

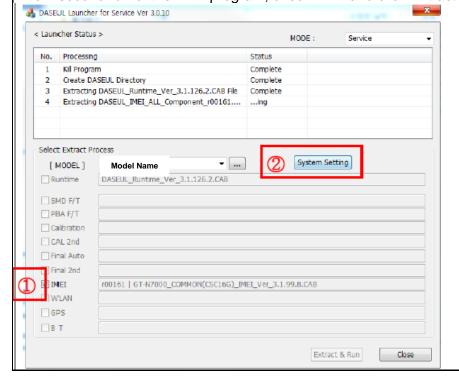


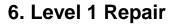




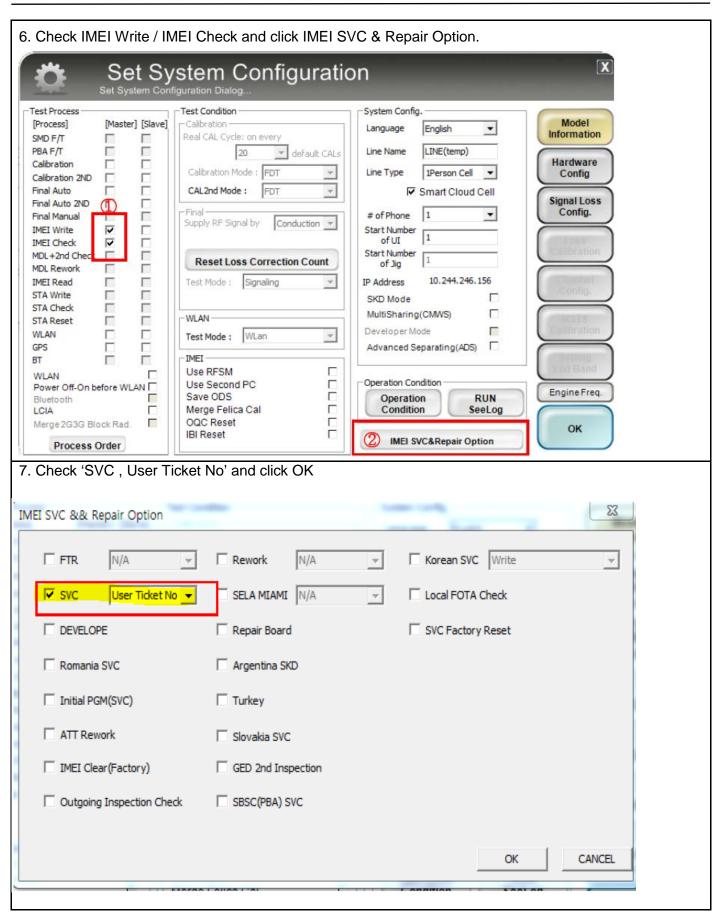


※Once you setup the setting, you don t have to do it again, unless there is change.
From second run of the IMEI program, check IMEI and click Extract & Run.



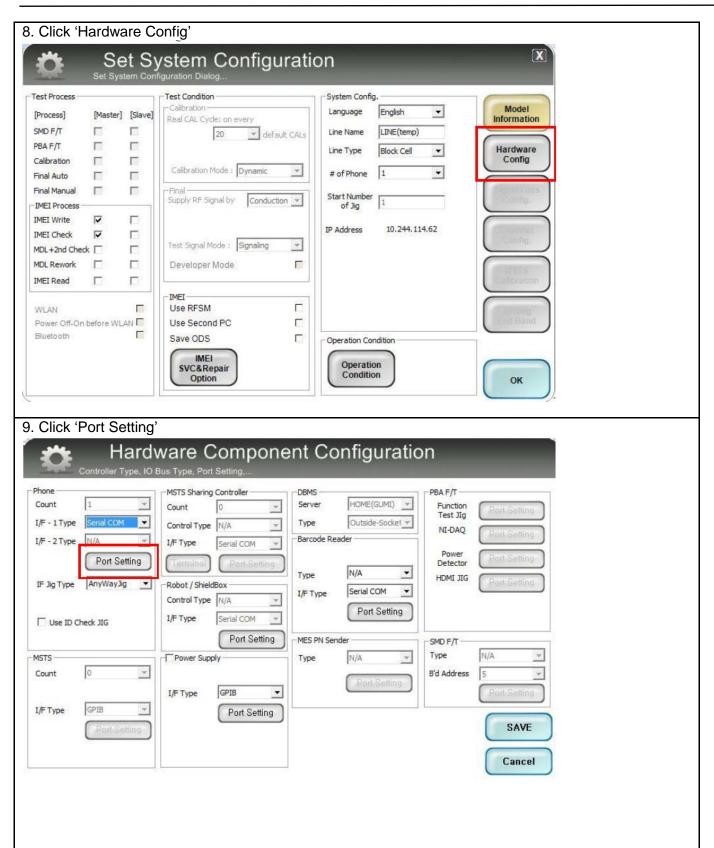


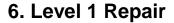




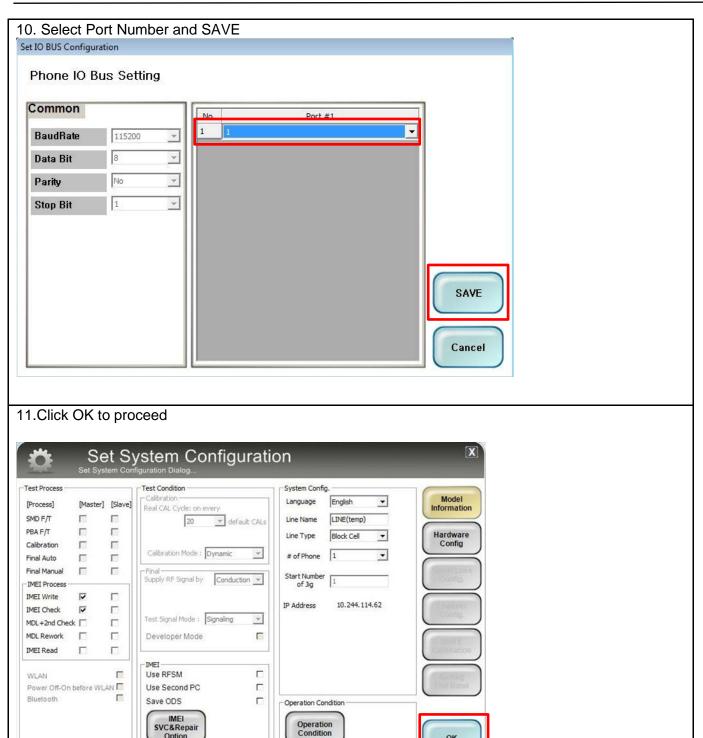






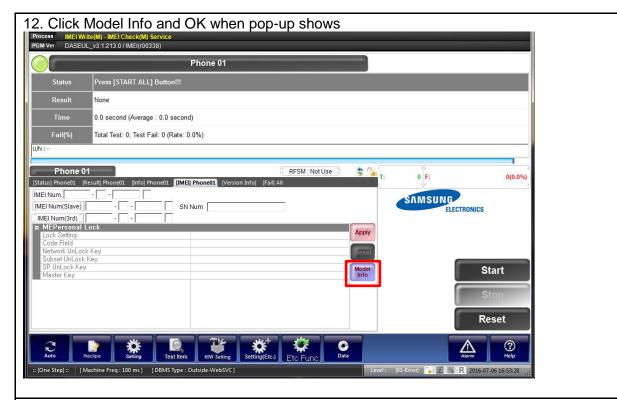












13. Click OK

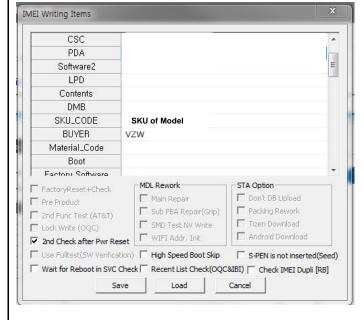




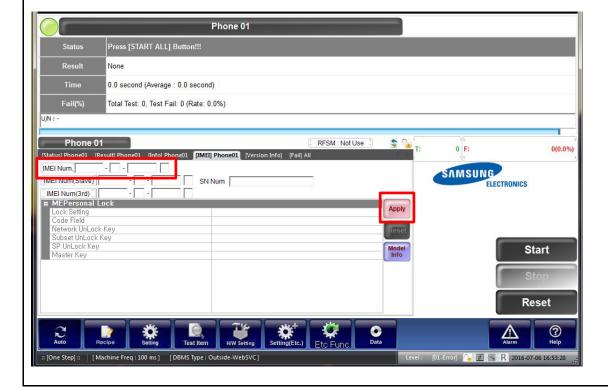


14. Input SKU_CODE and BUYER, then click Save button.



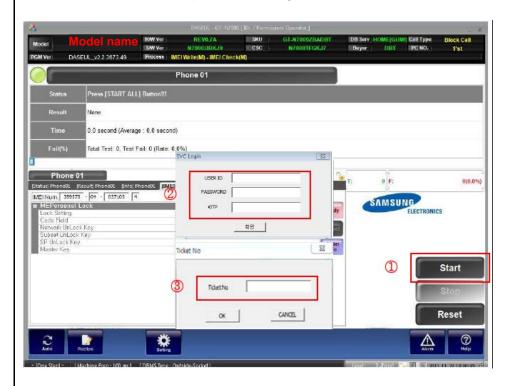


15. Input IMEI Number and click Apply





16. ① Click Start → ②Input IMEI writing ID and Password & OTP → ③Input Ticket No



M. OTP(One time Password): OTP is valid for 6 hours.

NEW IMEI OTP PASSWORD: SLD12HBJ

After that, you can get new OTP by click the "Forgotten your IMEI OTP PW or Crete new IMEI OTP PW" button.

STP Location: GSPN → Knowledge → HHP svc → Home

확인







- 17. Connect the phone to Anyway JIG
- When you connect the phone, the phone should be turned off.
 After connecting the phone, the phone will be booted automatically.

18. IMEI Writing Proceeding



19. IMEI Writing Success





6-3. RF Calibration

6-3-1. Required items in order to calibrate RF

- Installation program: RF Calibration Program
- Daseul_Launcher_vx.x.xx.exe
- Daseul_CAL_ALL_Runtime_x.x.xxx.x.CAB
- Model File (Model Name_OPEN_CALIBRATION_Ver_3.1.302.2.CAB)

* It is required to use the latest program.

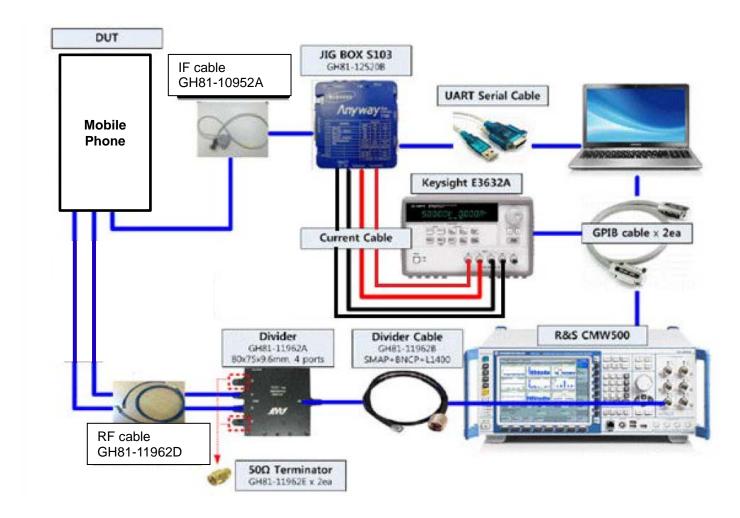
- Mobile Phone
- R&S CMW500
- E3632A Power Supply
- GPIB Cable (2ea)
- JIG BOX (GH81-12520B)
- Adapter (GH81-11888K)
- UART Serial Cable
- IF cable: GH81-10952A(7pin)

❖ Table of test cables

		GH81-11962D	
RF Cable (Manual)		1.2T, 102mm	
	GH81-11962A	GH81-11962B	GH81-11962E
4 Port Divider	Divider	Divider Cable	50Ω terminator



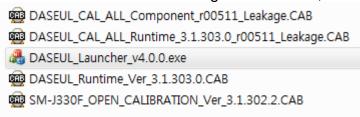
❖ Setting



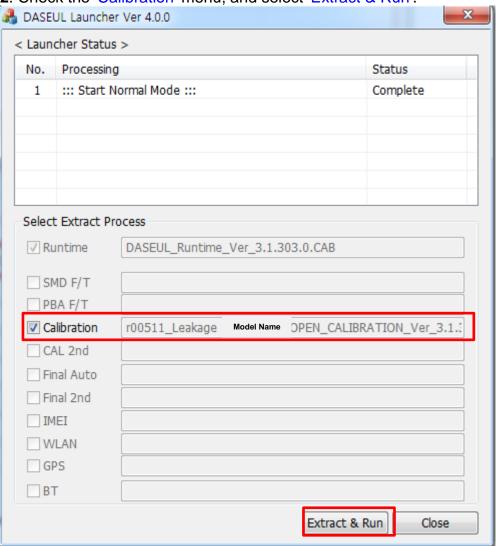


6-3-2. RF Calibration Program

1. Run the RF Calibration Program Launcher, 'DASEUL_Launcher_vx.x.xx.exe'.



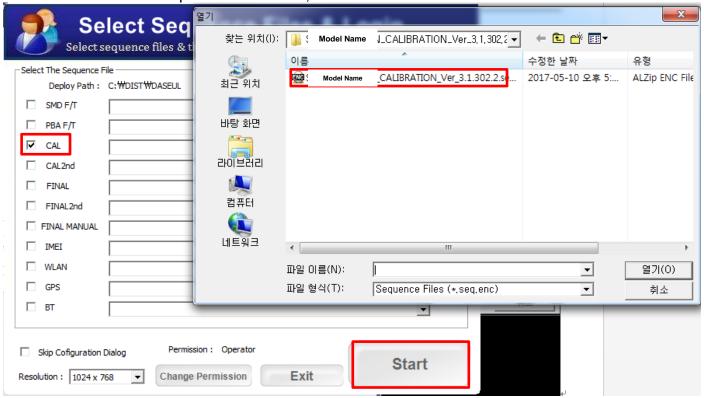
2. Check the 'Calibration' menu, and select 'Extract & Run'.

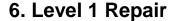






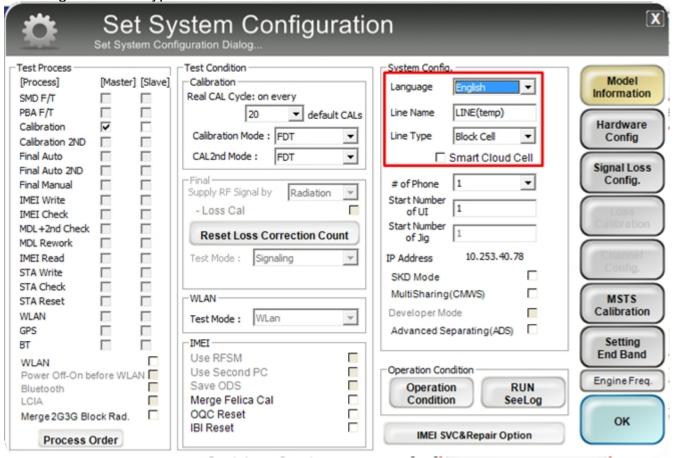
3. Check the 'CAL' and open the model file, then select 'Start' button.





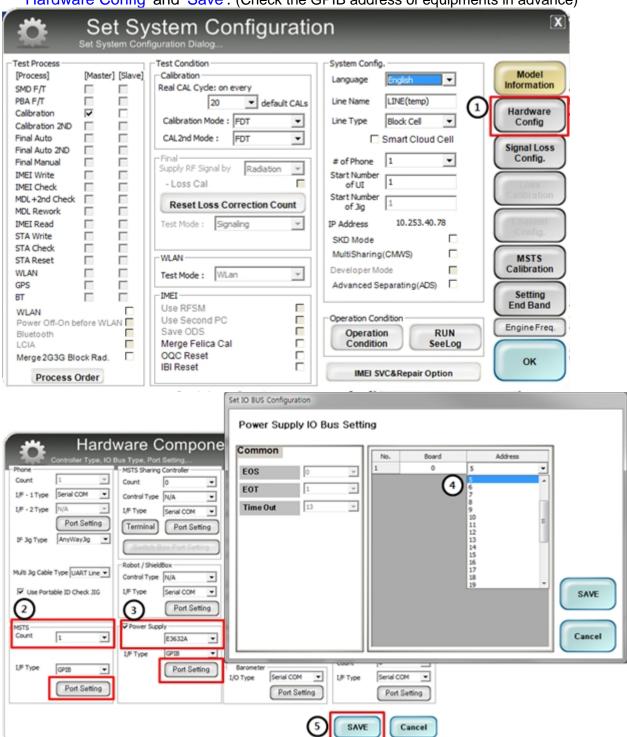


4. Change the Line Type to 'Block Cell' and disable 'Smart Cloud Cell'.





5. Set the GPIB address of MSTS(CMW500) and Power Supply(E3632A) to enter 'Hardware Config' and 'Save'. (Check the GPIB address of equipments in advance)





6. Press 'OK' to start RF Calibration after completing all settings.

